

ABSTRACT

BONDING APPARATUS COMPRISING **IMPROVED OSCILLATION AMPLIFICATION DEVICE**

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A bonding apparatus such as an ultrasonic transducer is provided that comprises an oscillation amplification device having a longitudinal axis and a substantially triangular cross-sectional area on a plane that is orthogonal to the longitudinal axis. An ultrasonic driver is coupled to the oscillation amplification device at a first position along the longitudinal axis and a bonding tool is mounted to the oscillation amplification device at a second position along the longitudinal axis spaced from the first position.

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(FIG. 2)